



IN THE UNITED STATES PATENT OFFICE

In re application of Nobuyuki IKEGUCHI

Serial No. 09/625,493

Filed : July 25, 2000

For : Glass fabric base material/thermosetting resin copper-clad laminate having a high-elasticity

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I, Nobuyuki IKEGUCHI, declare that :

1. I have conducted experiments which are described in the attached report;
2. I am the coinventor of the present invention, and a staff member of the Tokyo Factory of Mitsubishi Gas Chemical Company, Inc., and I have studied the outstanding Official Action dated September 13, 2002.
3. I graduated from Kumamoto University, the master's course in Chemistry course of Department of Industrial Chemistry in March 1972. I joined Mitsubishi Gas Chemical Company, Inc., in April 1972, and was attached to the Tokyo Laboratory in April 1972, and was attached to Tokyo Factory in April 1996 where I have been and am engaged in the study and development of electronic material and the like since April 1996.
4. All statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements and the like so made are punished by fines or imprisonment, or both, under section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

The 30th day of January, 2003

Nobuyuki Ikeguchi

Nobuyuki IKEGUCHI